



# BERGQUIST SIL PAD TSP Q2000

Known as BERGQUIST Q-PAD 3  
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## PRODUCT DESCRIPTION

Glass-Reinforced Grease Replacement Thermal Interface.

<b>Technology</b>	Silicone
<b>Appearance</b>	Black
<b>Reinforcement Carrier</b>	Fiberglass
<b>Total Thickness</b> , ASTM D374	0.127mm
<b>Application</b>	Thermal management, Thermally conductive adhesive
<b>Operating Temperature Range</b>	-60 to 180°C

## FEATURES AND BENEFITS

- Thermal impedance: 0.35°C-in<sup>2</sup>/W @ 50 psi
- Eliminates processing constraints typically associated with grease
- Conforms to surface textures
- Easy handling
- May be installed prior to soldering and cleaning without worry

## TYPICAL APPLICATIONS

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

BERGQUIST SIL PAD TSP Q2000 eliminates problems associated with thermal grease such as contamination of electronic assemblies and reflow solder baths. BERGQUIST SIL PAD TSP Q2000 may be installed prior to soldering and cleaning without worry.

When clamped between two surfaces, the elastomer conforms to surface textures thereby creating an air-free interface between heat-generating components and heat sinks. Fiberglass reinforcement enables BERGQUIST SIL PAD TSP Q2000 to withstand processing stresses without losing physical integrity. It also provides ease of handling during application.

## TYPICAL PROPERTIES

### Physical Properties

Hardness, Shore A, ASTM D2240	86
Flammability Rating, UL 94	V-0

## Electrical Properties

Dielectric Breakdown Voltage , ASTM D149, Vac	Non-Insulating
Dielectric Constant, ASTM D150 @ 1,000 Hz	NA
Volume Resistivity, ASTM D257, ohm-meter	1×10 <sup>2</sup>

## Thermal Properties

Thermal Conductivity , ASTM D5470, W/(m-K)	2.0
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## Thermal Performance vs. Pressure

TO-220 Thermal Performance, °C/W	
@ 10 psi	2.26
@ 25 psi	1.99
@ 50 psi	1.76
@ 100 psi	1.53
@ 200 psi	1.3
Thermal Impedance, ASTM D5470, °C-in <sup>2</sup> /W <sup>(1)</sup>	
@ 10 psi	0.65
@ 25 psi	0.48
@ 50 psi	0.35
@ 100 psi	0.24
@ 200 psi	0.16

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

## GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

## Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

## CONFIGURATIONS AVAILABLE

BERGQUIST SIL PAD TSP Q2000 are supplied in:

- Sheet form, roll form and die-cut parts
- With or without pressure-sensitive adhesive



**Conversions**

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$   
 $\text{kV/mm} \times 25.4 = \text{V/mil}$   
 $\text{mm} / 25.4 = \text{inches}$   
 $\text{N} \times 0.225 = \text{lb}$   
 $\text{N/mm} \times 5.71 = \text{lb/in}$   
 $\text{psi} \times 145 = \text{N/mm}^2$   
 $\text{MPa} = \text{N/mm}^2$   
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$   
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$   
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$   
 $\text{mPa}\cdot\text{s} = \text{cP}$

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The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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## Reference 1

## Данный компонент на территории Российской Федерации

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Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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